

# 2SK1335-VB Datasheet N-Channel 200 V (D-S) MOSFET

PRODUCT	SUMMARY	
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)
200	0.270 at V <sub>GS</sub> = 10 V	8

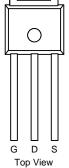
#### **FEATURES**

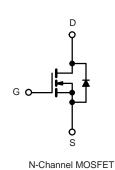
- Trench Power MOSFET
- 175 °C Junction Temperature
- PWM Optimized
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC





TO-251





## **APPLICATIONS**

· Primary Side Switch

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> =	= 25 °C, unless othe	rwise noted)			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	200	V	
Gate-Source Voltage		$V_{GS}$	± 20		
Continuous Drain Current (T <sub>.I</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 25 °C	I-	8		
Continuous Drain Current (1 <sub>J</sub> = 175 °C) <sup>3</sup>	T <sub>C</sub> = 125 °C	- I <sub>D</sub>	5		
Pulsed Drain Current		I <sub>DM</sub>	25	Α	
Continuous Source Current (Diode Conduction)		I <sub>S</sub>	5		
Avalanche Current		I <sub>AS</sub>	5		
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	18	mJ	
Maximum Power Dissipation	T <sub>C</sub> = 25 °C	P <sub>D</sub> 96 <sup>b</sup>		W	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	'D	3 <sup>a</sup>	] vv	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
lunation to Ambiant	t ≤ 10 s	R <sub>thJA</sub>	15	18	°C/W
Junction-to-Ambient <sup>a</sup>	Steady State	™thJA	40	50	
Junction-to-Case (Drain)	•	R <sub>thJC</sub>	0.85	1.1	

#### Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. See SOA curve for voltage derating.



Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	200			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2		4	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	$I_{DSS}$	V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50 μ <i>A</i>		
		V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	40			Α	
		$V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$		0.270			
Danie Course On Chata Besistance	R	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A, T <sub>J</sub> = 125 °C		0.300		0	
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A, T <sub>J</sub> = 175 °C		0.320		Ω	
		V <sub>GS</sub> = 6 V, I <sub>D</sub> = 3 A		0.310			
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 3 A		35		S	
Dynamic <sup>a</sup>							
Input Capacitance	C <sub>iss</sub>			800		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, F = 1 \text{ MHz}$		100			
Reverse Transfer Capacitance	C <sub>rss</sub>			50			
Total Gate Charge <sup>c</sup>	$Q_g$			34	51		
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 3 \text{ A}$		8		nC	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			12			
Gate Resistance	$R_g$		0.5		2.9	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			15	25		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 100 \text{ V}, R_{L} = 5.2 \Omega$		50	75	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 3 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		30	45	115	
Fall Time <sup>c</sup>	t <sub>f</sub>			60	90		
Source-Drain Diode Ratings and Char	acteristics (7	T <sub>C</sub> = 25 °C)					
Pulsed Current	I <sub>SM</sub>				5	Α	
Diode Forward Voltage <sup>b</sup>	V <sub>SD</sub>	I <sub>F</sub> = 3 A, V <sub>GS</sub> = 0 V		0.9	1.5	V	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 3 A, dI/dt = 100 A/μs		180	250	ns	

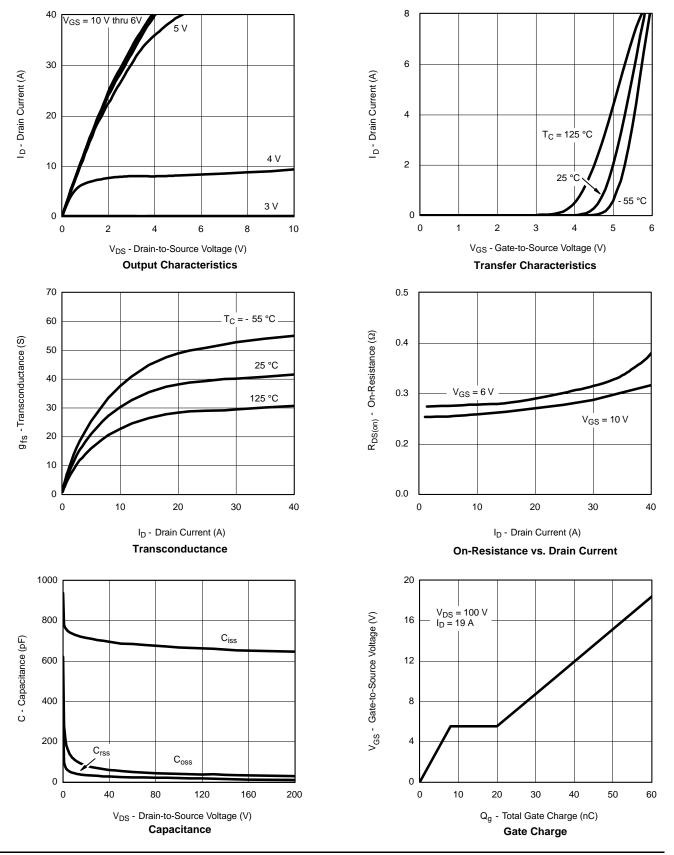
#### Notes:

- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

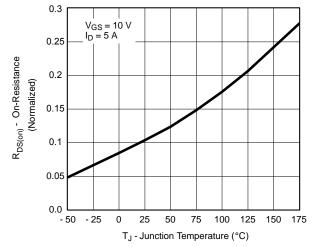


### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

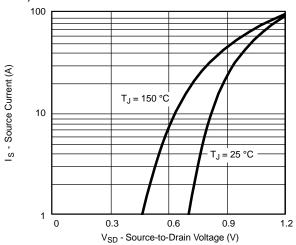




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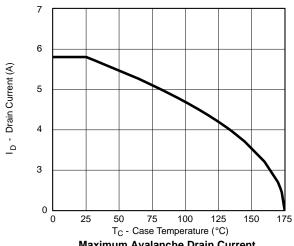


On-Resistance vs. Junction Temperature

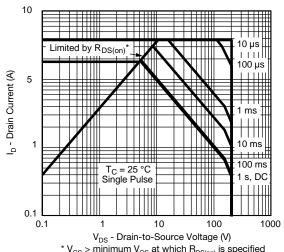


Source-Drain Diode Forward Voltage

#### THERMAL RATINGS



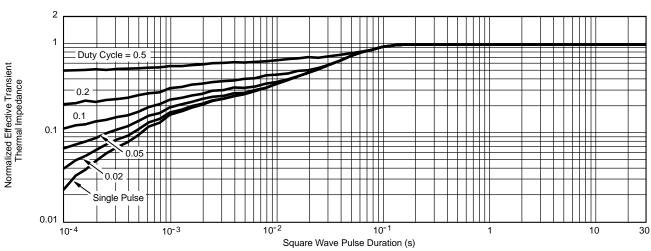
Maximum Avalanche Drain Current vs. Case Temperature



V<sub>DS</sub> - Drain-to-Source Voltage (V)

\* V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified

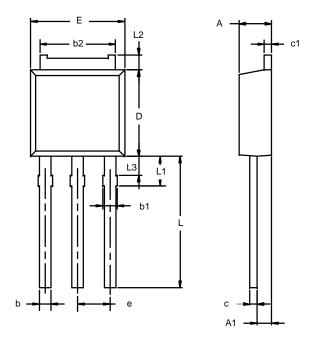
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case



### **TO-251AA**



Note: Dimension L3 is for reference only.

	MILLIN	IETERS	INC	HES	
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
<b>A</b> 1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
с1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
Е	6.48	6.73	0.255	0.265	
е	2.28	BSC	0.090 BSC		
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	



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